



Material Content Data Sheet



Sales Product Name				BTS307 E3062A		Issued		25. September 2017	
MA#				MA001115600					
Package				PG-TO263-5-2		Weight*		1496.62 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.704	0.25	0.25	2475	2475	
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158		
	non noble metal	iron	7439-89-6	0.790	0.05		528		
	non noble metal	copper	7440-50-8	788.527	52.68	52.75	526873	527559	
	non noble metal	aluminium	7429-90-5	1.588	0.11	0.11	1061	1061	
wire	non noble metal	aluminium	7429-90-5	1.588	0.11	0.11	1061	1061	
encapsulation	organic material	carbon black	1333-86-4	6.343	0.42		4238		
	inorganic material	antimonytrioxide	1309-64-4	13.263	0.89		8862		
	plastics	brominated resin	-	14.993	1.00		10018		
	plastics	epoxy resin	-	109.561	7.32		73206		
	inorganic material	silicondioxide	60676-86-0	432.477	28.90	38.53	288970	385294	
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6909	6909	
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5		
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2286	2291	
solder	non noble metal	tin	7440-31-5	0.066	0.00		44		
	noble metal	silver	7440-22-4	0.082	0.01		55		
	non noble metal	lead	7439-92-1	3.132	0.21	0.22	2093	2192	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		22		
	non noble metal	iron	7439-89-6	0.108	0.01		72		
	non noble metal	copper	7440-50-8	107.943	7.21	7.22	72125	72219	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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